

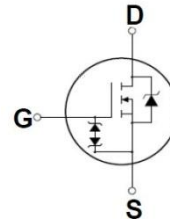
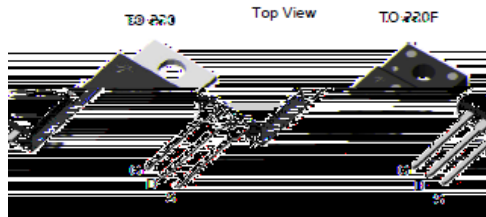
# TMP16N25Z(G)/TMPF16N25Z(G)

N-channel MOSFET

## Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification

$BV_{DSS}$	$I_D$	$R_{DS(on)}$
250V	16A	<0.24 $\Omega$



Device	Package	Marking	Remark
TMP16N25Z / TMPF16N25Z	TO-220 / TO-220F	TMP16N25Z / TMPF16N25Z	RoHS
TMP16N25ZG / TMPF16N25ZG	TO-220 / TO-220F	TMP16N25ZG / TMPF16N25ZG	Halogen Free

## Absolute Maximum Ratings

Parameter	Symbol	TMP16N25Z(G)	TMPF16N25Z(G)	Unit	
Drain-Source Voltage	$V_{DSS}$	250		V	
Gate-Source Voltage	$V_{GS}$	30		V	
Continuous Drain Current	$I_D$	$T_C = 25$	16	16 *	A
		$T_C = 100$	8.3	8.3 *	A
Pulsed Drain Current (Note 1)	$I_{DM}$	64	64 *	A	
Single Pulse Avalanche Energy (Note 2)	$E_{AS}$	368		mJ	
Repetitive Avalanche Current (Note 1)	$I_{AR}$	16		A	
Repetitive Avalanche Energy (Note 1)	$E_{AR}$	9.39		mJ	
Power Dissipation	$P_D$	$T_C = 25$	93.9	30.4	W
		Derate above 25	0.75	0.24	W/
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~150			
Maximum lead temperature for soldering purposes,	$T_L$	300			

\* Limited only by maximum junction temperature

## Thermal Characteristics

Parameter	Symbol	TMP16N25Z(G)	TMPF16N25Z(G)	Unit
Maximum Thermal resistance, Junction-to-Case	$R_{\theta JC}$	1.33	4.1	/W
Maximum Thermal resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	62.5	/W

## Electrical Characteristics : $T_C=25^\circ\text{C}$ , unless otherwise noted

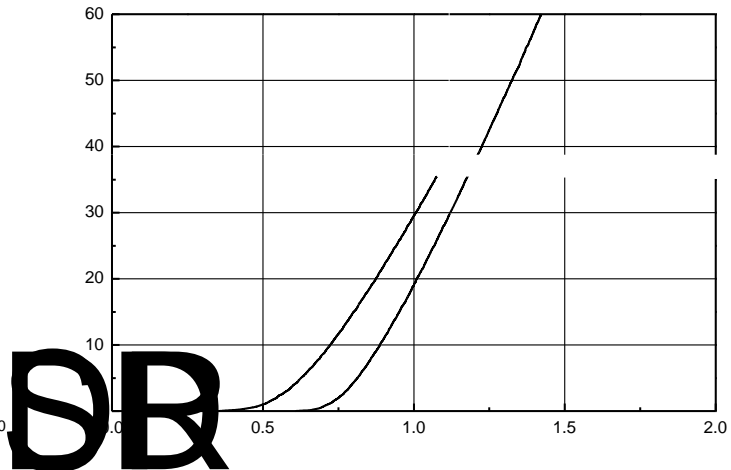
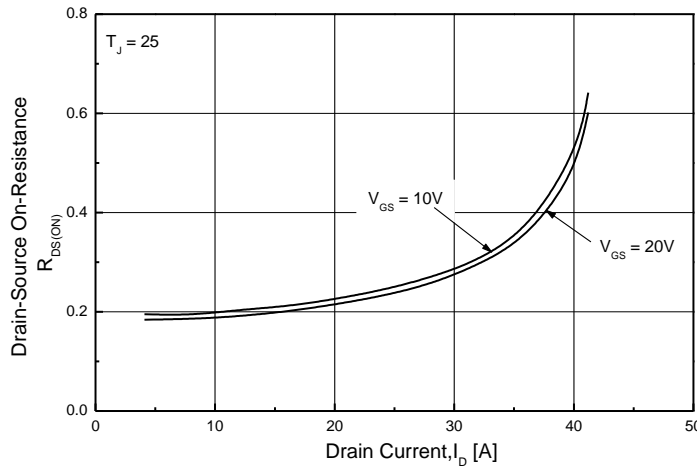
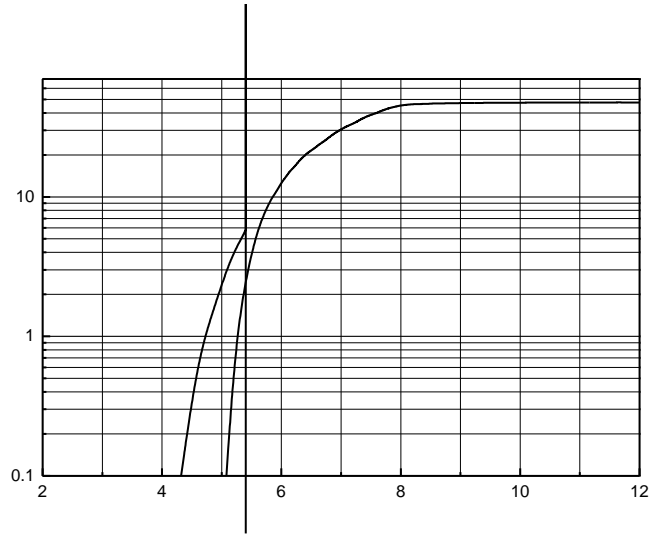
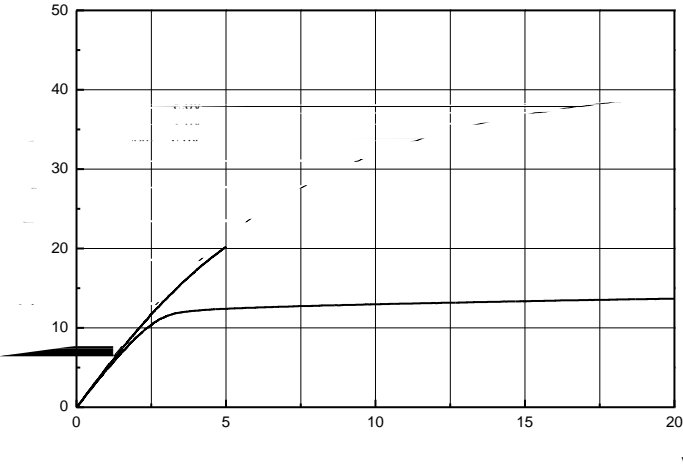
Parameter	Symbol	Test condition	Min	Typ	Max	Units
<b>OFF</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	250	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 250\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 200\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	$\mu\text{A}$
Forward Gate-Source Leakage Current	$I_{GSSF}$	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	$\mu\text{A}$
Reverse Gate-Source Leakage Current	$I_{GSSR}$	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	$\mu\text{A}$

<b>ON</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	3	--	5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 8\text{ A}$	--	0.2	0.24	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{GS} = 10\text{ V}, V_{DS} = 250\text{ V}, I_D = 8\text{ A}$	1.6	1.6	1.6	$\text{S}$

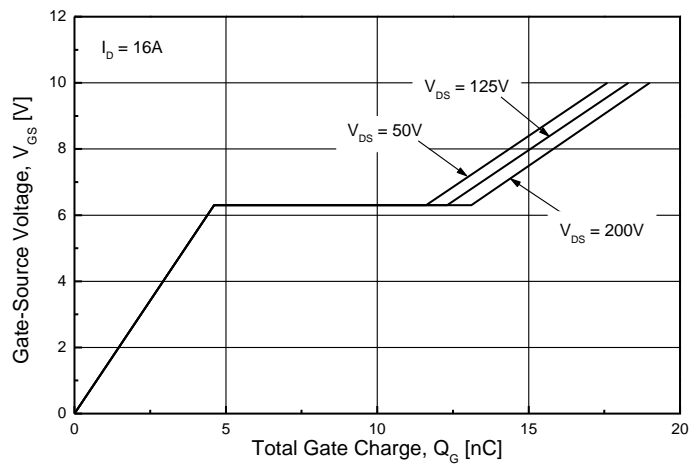
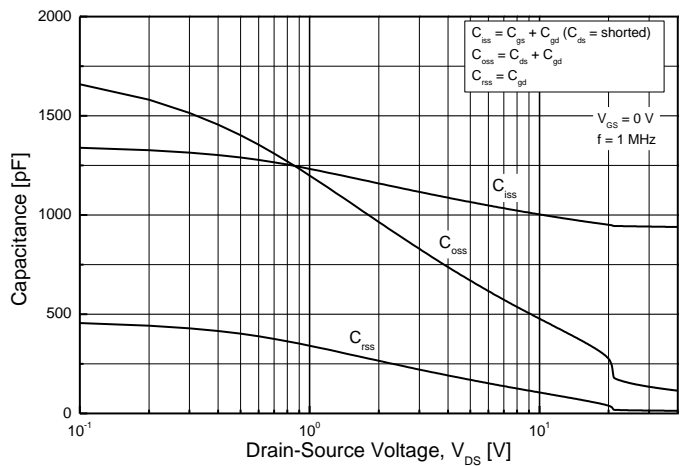

Note :

1. Repeated rating : Pulse width limited by safe operating area
2.  $L=2.3\text{mH}, I_{AS} = 16\text{A}, V_{DD} = 50\text{V}, R_G = 25^\circ\text{C}$  , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} = 16\text{A}, di/dt = 100\ \mu\text{s}^{-1}, V_{DD} = 50\text{V}, V_{DS} = 250\text{V}$ , Starting  $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

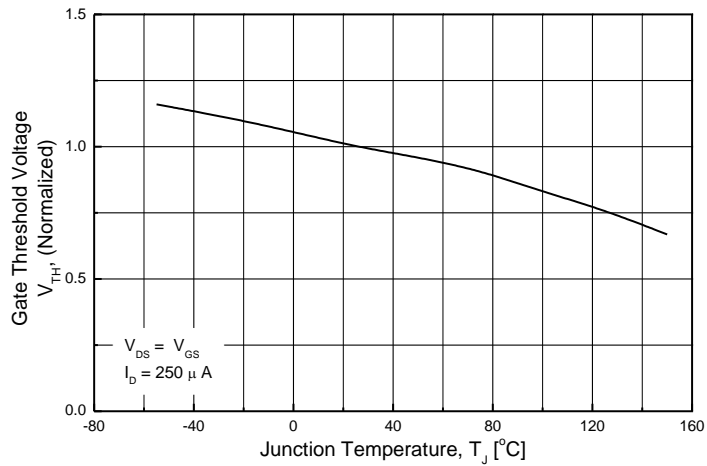
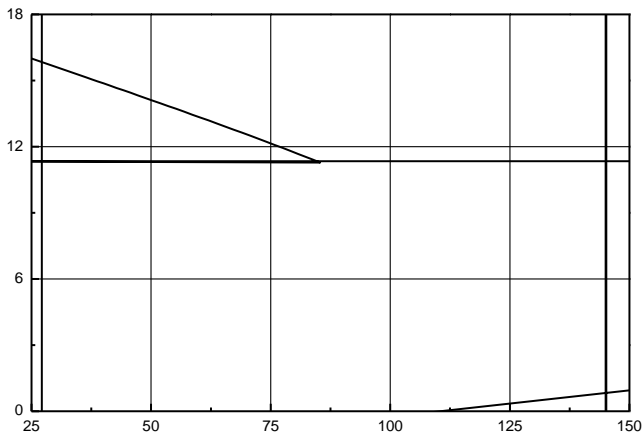
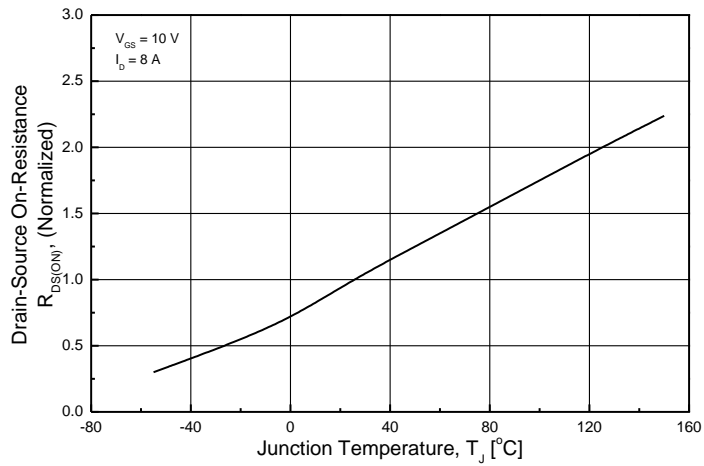
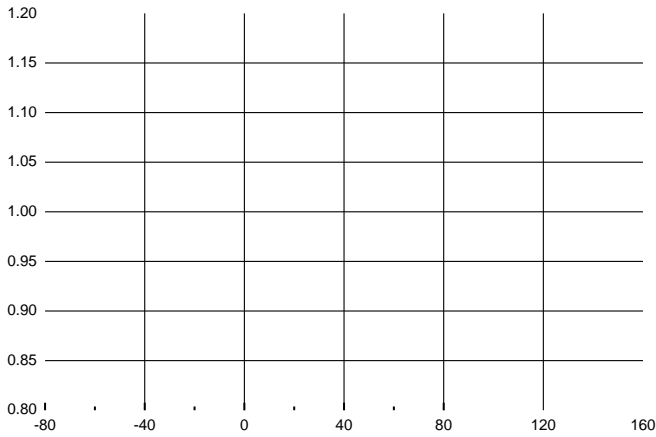
# TMP16N25Z(G)/TMPF16N25Z(G)



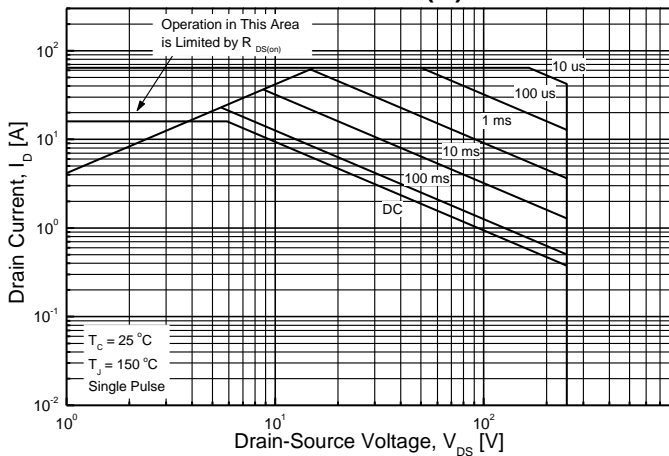
**DR**



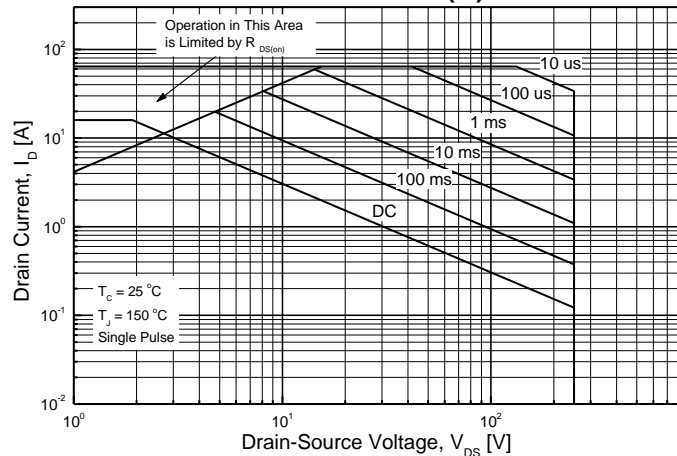
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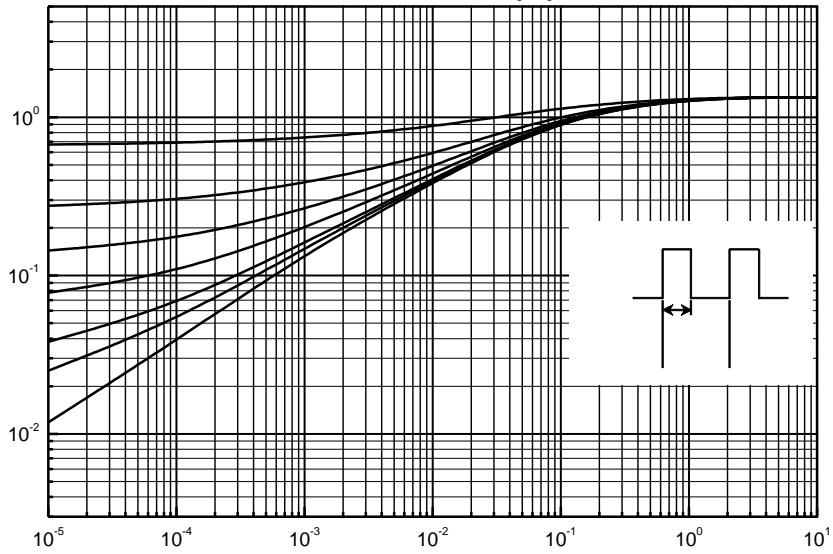
**TMP16N25Z(G)**



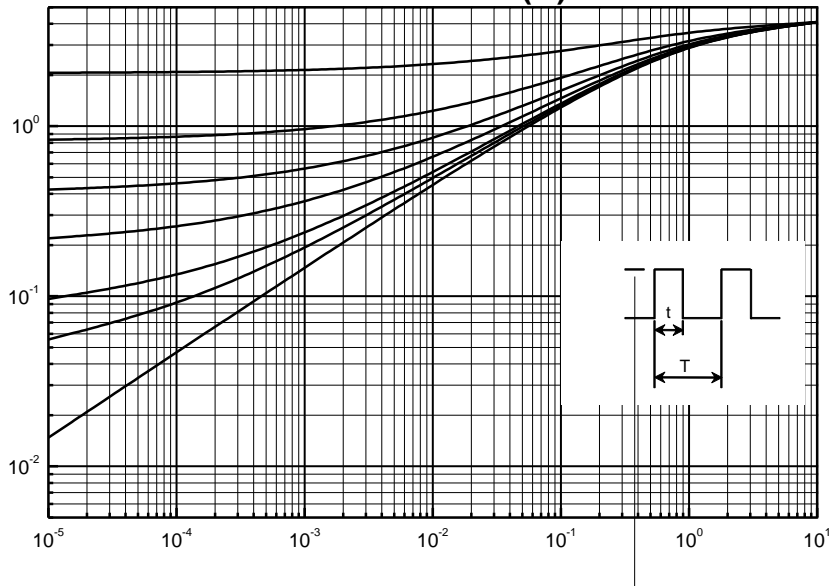
**TMPF16N25Z(G)**



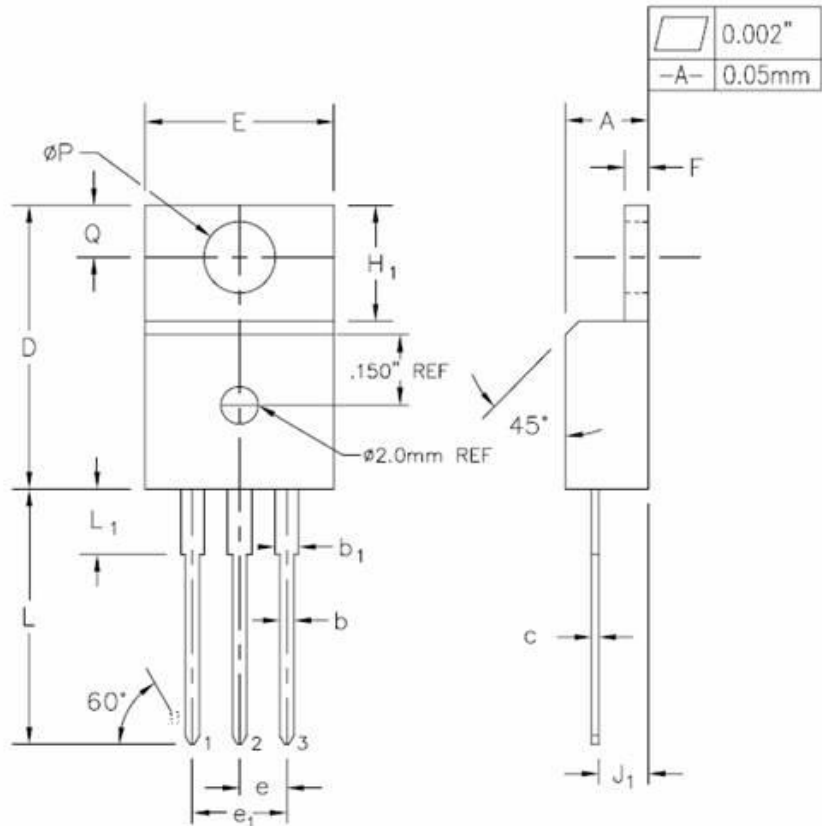
TMP16N25Z(G)



TMPF16N25Z(G)



TO-220AB-3L MECHANICAL DATA



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.170	0.180	4.32	4.57	
b <sub>1</sub>	0.028	0.036	0.71	0.91	
b	0.045	0.055	1.15	1.39	
c	0.014	0.021	0.36	0.53	
D	0.590	0.610	14.99	15.49	
E	0.395	0.411	10.02	10.44	
e	0.100 TYP.		2.54 TYP.		
e <sub>1</sub>	0.200 BSC		5.08 BSC		
F <sub>1</sub>	0.048	0.054	1.22	1.37	
H <sub>1</sub>	0.235	0.255	5.97	6.47	
J <sub>1</sub>	0.100	0.110	2.54	2.79	
L	0.530	0.550	13.47	13.97	
L <sub>1</sub>	0.130	0.150	3.31	3.81	
2	phi P	0.149	3.78	3.78	
Q	0.102	0.112	2.60	2.84	

TO-220F-3L MECHANICAL DATA

